

PCB LAYOUT
COMPONENT SIDE SHOW

MATERIAL:

1. HOUSING MATERIAL :GLASS FILLED POLYESTER UL94V-0.
2. CONTACT MATERIAL :PHOSPHOR BRONZE $t=0.35\text{mm}$
3. PLATING :SELECTING GOLD PLATING $1\mu\sim 50\mu$ OVER NICKEL IN CONTACT AREA. 150μ TIN PLATING OVER NICKEL IN SOLDER AREA.
4. SHIELD :0.25mm THICKNESS COPPER ALLY WITH NICKEL . PLATEL

ELECTRICAL:

1. VOLTAGE PATING :125 VAC RMS.
2. CURRENT PATING :1.5 AMP
3. CONTACT RESISTANCE :35 MILLIOHMS MAX
4. INSULATION RESISTANCE:1000 MEGOHMS MIN @ 500V DC.
5. DIELECTRIC WITHSTANDING RESISTANCE: 1000V AC RMS 60Hz. 1MIN

MECHANICAL:

1. DURRABILITY :750 CYCLES MIN
2. PCB RETENTION PRE-SOLDER :10LB MIN

ENVIRONMENTAL:

1. STORAGE : -40°C TO $+85^{\circ}\text{C}$.
2. OPERATION : -40°C TO $+85^{\circ}\text{C}$.
3. IR REFLOW SOLDERING

TEMPERRATURE:255~265°C (5~10 SECONDS)MATES WITH MODULAR PLUG CONFORMING TO FCC PART 68 SUBPART F.

Order Code:

ATRJ5821 - 8P - 8C - X - C

① ② ③ ④ ⑤

- ① SERIES NO:
 - ② NUMBER OF POSITIONS(8P, 6P, 4P)
 - ③ NUMBER OF CONTACTS(8C, 6C, 4C)
 - ④ Contact Plating
 - ⑤ Shield
- A:W/O Shield
 - B:Half Shield
 - C:Shield W/Eml
 - D:Shield W/O Eml
- G0:Gold flash
 - G1: 3U" Gold
 - G2: 5U" Gold
 - G3: 10U" Gold
 - G4: 15U" Gold
 - G5: 30U" Gold
 - SN: Tin

Unless Otherwise specified tolerance
X. ± 0.35 X.XX: ± 0.20
X.X: ± 0.25 X.XXX: ± 0.15

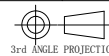


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SCALE: As Shown UNIT: mm
DRAW Wu Feng Rong DATE 22/03/2018
CHECK BobYang DATE 22/03/2018

TITLE:
RJ45 SIDE ENTRY SMT JACK

DRAWING NO: ATRJ5821-8P8C-X-C
PRODUCT NO: ATRJ5832-8P8C-X-C



REV	DESCRIPTION	DATE